

Sphere Alloy: Sn10Pb90

Sizes (mm): (inches):	0.100mm~0.450mm ± 0.01mm 0.004" ~ 0.018"		
Melting Point:	275°C		
Specific Gravity:	8.40		
Working Temp.	275~302 °C		

Composition Analysis (Weight %)

ltem	Compo	osition	Impurity								
IPC	Sn	Pb	Ag	Си	Sb	Zn	Fe	As	Bi	Cd	AI
JSTD -006B	10 ±0.5	Bal.	<0.01	<0.03	<0.05	<0.001	<0.02	<0.03	<0.03	<0.002	<0.001

Product Type and Weight

Туре	Solder Ball							
Dimen.	(0.100mm~0.450mm)± 0.01mm							
	sphericity deviation < 1.5% Illuminance ≥ 270 Lux							
Package	Package Material	Package Grade	Label					
T ackage	PP.Bottle	Anti Static	Part No. Description, Date					

Storage / Handling and Shelf Life

Shelf life is 1 year from date of purchase. Refrigeration is not recommended and does not extend shelf life. The container should remain unopened and not agitated. Normal fluctuations in room temperature will not affect shelf life. Avoid contamination of spheres from contact with foreign objects such as fingers or moisture.

Reflow Profile / Placement

Follow the reflow profile as recommended by the flux or solder paste manufacturer. This product is used in world wide semiconductor packaging processes, which is most commonly applied in automatic ball placement machines.

Health

This product, during handling or use, may be hazardous to health or the environment. Read the Material Safety Data Sheet and warning label before using this product.